

**KNEADING APPARATUS AND METHOD FOR PRODUCING SEMICONDUCTOR
ENCAPSULATING RESIN COMPOSITION**

ABSTRACT

5 The kneading apparatus 1 includes a casing 2, a pair
of elongated screws 4a, 4b rotatably provided in the
casing 2. The screws 4a, 4b are arranged parallel and
horizontally with respect to one another. The casing 2
has a main body 20 and a screw container 3 provided in
10 the casing 2. The screw container 3 defines a kneading
section 30 therein. The screw 4a includes a screw axis
41 having an outer periphery, a first screw member 42
provided on the outer periphery of the screw axis 41 and
a kneading member 43 provided on the outer periphery of
15 the screw axis 41. The first screw member 42 and
kneading member 43 are provided in the kneading section
30. The screw 4a, the first screw member 42 and the
kneading member 43 respectively have core portions 411,
412, 413 having a surface and outer layers 45
20 respectively provided on the surfaces of the core
portions 411, 412, 413. The screw container 3 and the
outer layers 45 are constituted of a nonmetallic
material.

25 Figure 3 accompanies the abstract.